"Forging A Better Future"

The International Conference On

ADVANCES IN MATERIALS AND PROCESSING TECHNOLOGIES

AMPT 2009

Website: http://www.iiu.edu.my/ampt2009

26 - 29 October, 2009

Kuala Lumpur, Malaysia



Organized By:



Faculty of Engineering, International Islamic University Malaysia.

## Malaysia **Q** Kuala Lumpur

Malaysia is located in Southeast Asia with a total landmass of 329,847 square kilometres. The country comprises of two regions which are Peninsular Malaysia and Malaysian Borneo. Malaysian population is over 25 millions with different ethnic groups of Malays, Chinese, Indian and others. The climate of Malaysia is tropical with the temperature of 25–30°C. Its sun-drenched beaches, enchanting islands, diverse flora and fauna, forest retreats and magnificent mountains are among the best in this region.

Kuala Lumpur, the capital of Malaysia, brings together Malaysia's past and present cultures, and remarkable natural treasures. One can experience the rich culture of historic Kuala Lumpur through its art galleries, diverse architectures and craft centres. The natural beauty and variety of local plants and animals through its botanical and bird parks are unparallel. The delights of Malay, Chinese, Indian and Nyonya cuisines are extremely enjoyable. As the entry point for most visitors and the meeting point of the country's many attractions, kuala Lumpur is a grand gateway to a fascinating destination.



## Introduction & Background

#### International Islamic University Malaysia (IIUM)

The International Islamic University Malaysia (IIUM) was established in 1983 by the Government of Malaysia and co-sponsored by Organization of Islamic Conference (OIC). Using English as a medium of instruction, the university currently serves as a higher learning institution for 20,000 students from more than 90 countries. In 2008 IIUM celebrated the 25th Anniversary.

#### AMPT Conference

Advances in Materials and Processing Technologies (AMPT) conference founded in 1993 at the Dublin City University, Dublin, Ireland and was held there in 1993, 1995, 1999 and 2003. Moreover, it has taken place so far in Portugal in 1997, Malaysia in 1998, Spain in 2001, Poland in 2004, USA in 2006, South Korea in 2007 and Kingdom of Bahrain in 2008. The conference provides a chance for academics, researchers, scientists and engineers to meet and exchange innovative ideas and information in all aspects of advances in materials and processing technologies.



#### AMPT Steering Committee

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IIUM, Malaysia

(Sponsorships from Saudi Arabia & the Gulf region)

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# Conference Venue Accommodation

The conference will take place at the The legend Hotel of Kuala Lumpur. It is the five stars business class hotel in the heart of Kuala Lumpur. The hotel is located 10 minutes away from the city's bustling 'Golden Triangle'. It is located next to Malaysia's premier convention complex, the Putra World Trade Centre (PWTC) and next to the Putra Mall. The hotel is easily accessible by public transport and is within a walking distance to the Putra Light Rail Transit (LRT) station and the PWTC Komuter Station.

An exceptional hotel with a level of hospitality that goes beyond normal range of luxurious hotel, The Legend Hotel is an apt ambassador of the legendary Malaysian charm and friendliness, accompanied by uncompromising world - class standards. Arrangements will be made with the hotel for accommodation of the AMPT 2009 delegates with discount rates. Detail information will be available in the conference website.

(Website: http://www.iiu.edu.my/ampt2009)



Conference Topics



The scope of the AMPT 2009 Conference will cover all topics of processing of materials including but not limited to metals, ceramics, polymers and composites in the following areas:

#### 1. Forming Processes:

Bulk forming, Net-shape, Manufacturing, Sheet Forming, Spinning, Hydro-forming, High rate forming processes, Powder Forming–compaction, Sintering, Injection Molding, CIP, HIP.

#### 2. Casting and Joining:

Casting and Solidification Processes, Welding, Brazing and Soldering, Mechanical Fastening and Adhesive Bonding, Heat Treatment, Thermomechanical Treatments.

#### 3. Materials:

Metallic materials, Ceramics, Polymers, MMC, PMC, CMC, Biomaterials, Magnetic materials, Electronic materials, Semiconductor and other advanced materials.

#### 4. Materials Removal Processes:

Metal Cutting, High Speed Machining, Hot Machining, Grinding, Advanced machining processes, ECM, EDM, WJM.

#### 5. High Energy Beam Processing:

Laser and Electron Beam in Cutting, Welding, Surface Melting, Surface Hardening.

#### 6. Precision Engineering and Nanotechnology:

Electroforming, Microforming, Microalloying, Near Net - shape Manufacturing, MEMS, Nanofabrication, Nanofilms.

#### 7. Surface Engineering:

Surface coating by Electro and Electroless Plating, PVD, CVD, Thermal Coating, Nitriding, Carburising, Boriding.

#### 8. Computer Aided Engineering:

FEA, CAD, CAM, CIM, Rapid Prototyping, Modelling and Simulation.

#### 9. Management in Manufacturing and Environmental Issue:

Industrial Pollution, Safety, Ergonomics and Ethical Aspects, Sustainable Design in Manufacturing, Waste Management and Recycling, Quality Control, Management and Economic Aspects in Production Processes.

**Publication** 

An extended abstract of about 300 words should be submitted to the conference secretariat. Authors of accepted abstracts will be notified to submit full papers. All papers accepted for presentation at the AMPT 2009 conference will be peer reviewed for publication in special issues of the journals:

- 1. Advanced Materials Research.
- 2. Journal of Achievements in Materials and Manufacturing Engineering
- 3. Arabian Journal of Science and Engineering.
- 4. Journal of Mechanical Science and Technology.

Additionally, with the agreements of the Editors, a small number of selected papers will be directed to the following journals for further review for publication in regular issues:

- 1.CAD Computer-Aided Design.
- 2. International Journal of Mechanical Sciences
- 3. Surface and Coatings Technology
- 4. The International Journal of Material Forming

A book of Abstracts will be published by the conference organizers and made available to all the delegates attending the conference. No separate conference proceedings will be published.

#### Important Dates

<ul> <li>Submission of Abstract</li> </ul>	31 March, 2009
Acceptance of Abstract	15 April, 2009
<ul> <li>Submission of Full Paper</li> </ul>	31 July, 2009
<ul> <li>Acceptance of Full Paper</li> </ul>	1 <sup>st</sup> Sept, 2009
• Early Bird Registration	15 August, 2009

#### **Registration Form**

#### International Islamic University Malaysia Gombak, Kuala Lumpur, Malaysia

Name:
Institution:
Postal Address:
Tel:( )
Fax: ( )
Email:
Please tick ( $\checkmark$ ) in the appropriate boxes below:
I plan to attend the conference without paper presentation
I intend to present a paper at the conference and enclose a copy of the abstract entitled

#### **CONFERENCE FEE AND REGISTRATION**

Registration fees	Early Bird (Paid by 15 August 2009)	Regular
International Participants	USD 450	USD 550
Local Participants	RM 1200	RM 1500
Student (International)	USD 300	USD 350
Student (Local)	RM 750	RM 850

The registration fee includes the cost of the conference proceedings admission to all technical sessions, presentation of up to two papers, banquet dinner, meals and refreshments.

Payment of registration fee can be made by credit card online through <a href="http://www.iiu.edu.my/ampt2009">http://www.iiu.edu.my/ampt2009</a> or by bank draft payable to "IIUM (AMPT2009)".

Contact us at:

Secretary, AMPT 2009

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International Islamic University Malaysia
P.O. Box 10, 50728 Kuala Lumpur, Malaysia
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Website: http://www.iiu.edu.my/ampt2009

#### Website: http://www.iiu.edu.my/ampt2009

#### 1) ELITE PLATINUM SPONSOR: OVER US\$ 75,000

- a Company name and logo of appropriate sizes will be published in all the conference publicity materials as Elite Platinum Sponsor.
- b Entitled for space at the exhibition hall (if required).
- c Five non-author delegates from the sponsoring company may attend the conference with full package (registration + accommodation) free of charge.
- d Publicity materials will be included in the conference pack.
- e Company name and logo with a brief profile will be published in the conference web site which shall be connected to the Sponsor's web site.
- f Two full page advertisement shall be provided in the Exhibition Guide (if any) to the Elite Platinum Sponsor.
- g Sponsored company will be honored with a Plaque by the Conference Patron at the Opening Ceremony.
- h Executive Officers will be treated as VIPs during the event and official lunches and dinner.
- i Large Company logo will be displayed in the conference hall along with the conference banner and outside lobby.
- i Company name and logo will be published in the program book.
- k A honorary Gold medal will be awarded.
- I Honored with the conference dinner.

#### 2) PLATINUM SPONSOR: US\$ 50,000 TO US\$ 70,000

- a Company name and logo of appropriate sizes will be published in all the conference publicity materials as Platinum Sponsor.
- b Entitled for space at the exhibition hall (if required).
- c Three non-author delegates from the sponsoring company may attend the conference with full package (registration + accommodation) free of charge.
- d Publicity materials will be included in the conference pack.
- e Company name and logo with a brief profile will be published in the conference web site which shall be connected to the Sponsor's web site.
- f Two full page advertisement shall be provided in the Exhibition Guide (if any) to the Platinum Sponsor.
- g Sponsored company will be honored with a Plaque by the Conference Patron at the Opening Ceremony.
- h Executive Officers will be treated as VIPs during the event and official lunches and dinner.
- i Large Company logo will be displayed in the conference hall along with the conference banner and outside lobby.
- j Company name and logo will be published in the program book.
- k A honorary Gold medal will be awarded.
- I Honored with the conference dinner.

#### 3) ELITE GOLD SPONSOR: US\$ 30,000 TO US\$ 45,000

- a Company name and logo of appropriate sizes will be published in all the conference publicity materials as Elite Golden Sponsor.
- b Entitled for space at the exhibition hall (if required).
- Two non-author delegates from the sponsoring company may attend the conference with full package (registration + accommodation) free of charge.
- d Publicity materials will be included in the conference pack.
- e Company name and logo with a brief profile will be published in the conference web site which shall be connected to the Sponsor's web site.
- f A full page advertisement shall be provided in the Exhibition Guide (if any) to the Elite Gold Sponsor.
- Sponsored company will be honored with a Plaque by the Conference Patron at the Opening Ceremony.
- h Executive Officers will be treated as VIPs during the event and official lunches and dinner.
- i One banner will be displayed in the conference hall, lobby and exhibition hall.
- i Company name and logo will be published in the program book.
- k A honorary Gold medal will be awarded.
- I Honored with the conference dinner.

# 12 AMPT 2009 Benefits Offered to Sponsoring Company Website: http://www.iiu.edu.my/ampt2009

#### 4) GOLD SPONSOR: US\$ 15,000 TO US\$ 25,000

- a Company name and logo of appropriate sizes will be published in all the conference publicity materials as Golden Sponsor.
- b Entitled for space at the exhibition hall (if required).
- c Two non-author delegates from the sponsoring company may attend the conference with full package (registration + accommodation) free of charge.
- d Publicity materials will be included in the conference pack.
- e Company name and logo with a brief profile will be published in the conference web site which shall be connected to the Sponsor's web site.
- f A full page advertisement shall be provided in the Exhibition Guide (if any) to the Golden Sponsor.
- g Sponsored company will be honored with a Plaque by the Conference Patron at the Opening Ceremony.
- h Executive Officers will be treated as VIPs during the event and official lunches and dinner.
- i One banner will be displayed in the conference hall, lobby and exhibition hall.
- Company name and logo will be published in the program book.
- k A honorary Gold medal will be awarded.
- I Honored with the conference dinner.

#### 5) SILVER SPONSOR: US\$ 5,000 TO US\$ 10,000

- a Company name and logo of appropriate sizes will be published in all the conference publicity materials as Silver Sponsor.
- b Entitled for space at the exhibition hall (if required).
- c One non-author delegate from the sponsoring company may attend the conference with full package (registration + accommodation) free of charge.
- d Publicity materials will be included in the conference pack.
- e Company name and logo with a brief profile will be published in the conference web site which shall be connected to the Sponsor's web site.
- f A half page advertisement shall be provided in the Exhibition Guide (if any) to the Silver Sponsor.
- a Sponsored company will be honored with a Plaque by the Conference Patron at the Opening Ceremony.
- h Executive Officers will be treated as VIPs during the event and official lunches and dinner.
- i One banner will be displayed in the conference hall.
- Company name and logo will be published in the program book.
- k A honorary Silver medal will be awarded.
- I Honored with the conference dinner.

#### 6) BRONZE SPONSOR: US\$2,000 TO US\$ 4,500

- a Company name and logo of appropriate sizes will be published in all the conference publicity materials as Bronze Sponsor.
- b One non-author delegate from the sponsoring company will be invited in the conference dinner free of charge.
- c Publicity materials will be included in the conference pack.
- d Company name and logo with a brief profile will be published in the conference web site which shall be connected to the Sponsor's web site.
- e A quarter page advertisement shall be provided in the Exhibition Guide (if any) to the Bronze Sponsor.
- f Sponsored company will be honored with a Plaque by the Conference Patron at the Opening Ceremony.
- g Executive Officers will be treated as VIPs during the event and official lunches.
- h One banner of Bronze Sponsor will be displayed in the conference hall.
- i Company name and logo will be published in the program book.

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#### 7) CONFERENCE DINNER SPONSOR: US\$ 20,000

- a Company name and logo will be published in all the conference publicity materials as Conference Dinner Sponsor.
- b Entitled for space with at the exhibition hall (if required).
- c Two non-author delegates from the sponsoring company may attend the conference with full package (registration + accommodation) free of charge.
- d Publicity materials will be included in the conference pack.
- e Company name and logo with a brief profile will be published in the conference web site which shall be connected to the Sponsor's web site.
- f A full page advertisement shall be provided in the Exhibition Guide (if any ) for the Dinner Sponsor.
- g Sponsored company will be honored with a Plaque by the Conference Patron at the opening ceremony.
- Executive Officers will be treated as VIPs during the event and at the official lunches and dinner.
- i One banner will be displayed at the Dinner Venue.

#### 8) LUNCHEON SPONSOR: US\$ 10,000

- Company name and logo will be published in all the conference publicity materials as Luncheon Sponsor.
- b Entitled for space at the exhibition hall (if required).
- c One non-author delegate from the sponsoring company may attend the conference with full package (registration + accommodation) free of charge.
- d Publicity materials will be included in the conference pack.
- e Company name and logo with a brief profile will be published in the conference web site which shall be connected to the Sponsor's web site.
- f A half page advertisement shall be provided in the Exhibition Guide ( if any ) for the Luncheon Sponsor.
- g Sponsored company will be honored with a Plaque by the Conference Patron at the opening ceremony.
- h Executive Officers will be treated as VIPs during the event and at the official lunches and dinner.
- i Extra 4 additional Invitations will be provided for Lunch
- j One banner will be displayed at the Lunch Venue.

#### 9) OPENING CEREMONY RECEPTION SPONSOR: US\$ 4,000

- a Company name and logo of appropriate sizes will be published in all the conference publicity materials as Opening Ceremony Sponsor.
- b Three persons from the sponsoring company will be invited to the conference dinner free of charge.
- c Publicity materials will be included in the conference pack.
- d Company name and logo with a brief profile will be published in the conference web site which shall be connected to the Sponsor's web site.
- e A quarter page advertisement shall be provided in the Exhibition Guide (if any) to the Opening Ceremony Reception Sponsor.
- f Sponsored company will be honored with a Plaque by the Conference Patron at the Opening Ceremony.
- g Executive Officers will be treated as VIPs during the event and official lunches.
- h One banner of the Sponsor will be displayed in the conference hall.
- i Company name and logo will be published in the program book.

#### 10) W. JOHNSON INTERNATIONAL GOLD MEDAL SPONSOR: US\$ 4,000

- a Company name and logo of appropriate sizes will be published in all the conference publicity materials as W. Johnson Intl. Gold Medal Sponsor.
- b Three persons from the sponsoring company will be invited to the conference dinner free of charge.
- c Publicity materials will be included in the conference pack.
- d Company name and logo with a brief profile will be published in the conference web site which shall be connected to the Sponsor's web site.
- A quarter page advertisement shall be provided in the Exhibition Guide ( if any ) to the Intl.Gold Medal Sponsor.
- f Sponsored company will be honored with a Plaque by the Conference Patron at the Opening Ceremony.
- g Executive Officers will be treated as VIPs during the event and official lunches.
- h One banner of the Sponsor will be displayed in the conference hall.
- i Company name and logo will be published in the program book.



## Website: http://www.iiu.edu.my/ampt2009 SPONSORSHIP REGISTRATION

AMPT Conference & Exhibition , 26 - 29 October 2009 Grand Ballroom , Best Western Premier Seri Pacific Hotel, Kuala Lumpur, Malaysia

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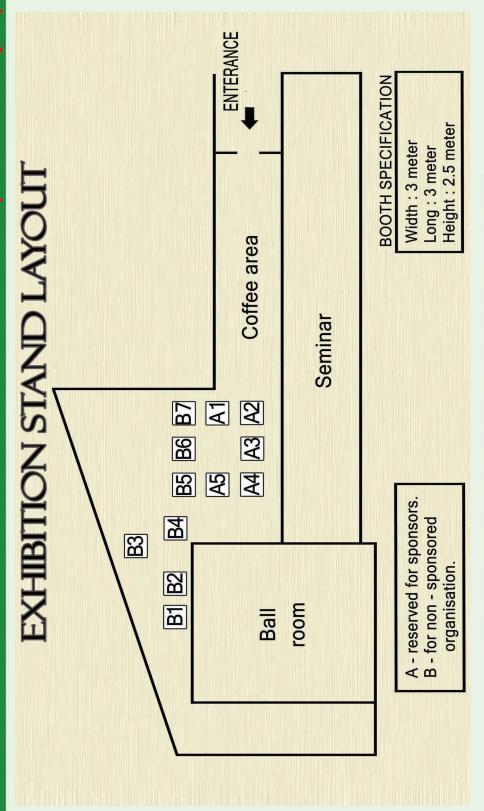
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0	Gold Sponsor	US\$ 15,000 TO US\$ 25,000
0	Silver Sponsor	US\$ 5,000 TO US\$ 10,000
0	Bronze Sponsor	US\$2,000 TO US\$ 4,500
0	Conference Dinner	US\$ 20,000
0	Luncheon	US\$ 10,000
0	Opening Ceremony	US\$ 4,000
0	W. Johnson Gold Medal	US\$ 4,000

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For non - sponsored organisation the exhibition booth cost: US\$ 2000